

Title of Change:	Capacity expansion for NCP114xSNxxxT1G products in TSOP5 package at On Semiconductor, Leshan, China.		
Proposed first ship date:	25 July 2017 or earlier with customer approval.		
Contact information:	Contact your local ON Semiconductor Sales Office or < <u>Shannon.riggs@onsemi.com</u> >		
Samples:	Contact your local ON Semiconductor Sales Office		
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or < <u>tomas.vajter@onsemi.com</u> >.		
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <pcn.support@onsemi.com>.</pcn.support@onsemi.com>		
Change Part Identification:	Affected products will be identified with date code and manufacturing location indicators. Additionally package shipping labels will indicate the country of origin location. Product shipped after PCN effectivity, or earlier based on customer acceptance, may be sourced from the new location, or any of the previously qualified locations.		
Change category:	🗆 Wafer Fab Change 🛛 Assembly Change 🖾 Test Change 🔲 Other		
Change Sub-Category(s): Manufacturing Site Change/ Manufacturing Process Changer Sites Affected:			
	oplicable ON Semiconductor site(s) : External Foundry/Subcon site(s) ON Leshan, China		

Description and Purpose:

ON Semiconductor is qualifying additional assembly and test manufacturing capacity for NCP114xSNxxxT1G products in TSOP5 package in the Leshan, China manufacturing facility. This Final PCN is providing the details pertinent to the change. This change represents capacity expansion, and upon expiration of the PCN (or earlier with customer acceptance), product may be sourced from either ON Semiconductor Leshan, or any of the previously approved manufacturing locations.

Material to be changed	Before Change Description	After Change Description
Leadframe	CDA194	CDA194 (no change)
Mold Compound	EME G600FB	EME G600FB (no change)
Die attach	Ероху, АВ8008	Eutectic,
Bond Wire	Au, 0.8mil	Au, 0.8mil (no change)



Reliability Data Summary:

QV DEVICE : NCP114xSNxxxT1G

RMS: 37863, 38381

PACKAGE: TSOP5

Test	Specification	Condition	Interval	Results
HTOL	JESD22-A108	Ta= 125°C, 100 % max rated Vcc	1008 hrs	0/80
HTSL	JESD22-A103	Ta= 150°C	1008 hrs	0/240
TC-PC	JESD22-A104	Ta= -65°C to +150°C	500 сус	0/240
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/240
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/240
PC	J-STD-020 JESD-A113	MSL 1 @ 260 °C		
RSH	JESD22- B106	Ta = 265C, 10 sec		0/90
SD	JSTD002	Ta = 245C, 10 sec		0/ 45
ED	Electrical Distribution	Critical Parameters, Ta=-40C, 25C, 85C		Cpk>1.67, Pass
PD Physical Dimensions		Per Case outline		Pass
BPS	MILSTD883 Method 2011	Cond C.		Cpk>1.67, Pass
BS	AECQ100			Cpk>1.67, Pass
SAT	J-STD-020 JESD-A113			Pass

Electrical Characteristic Summary:

Electrical characteristics are not affected; all datasheet parameters remain unchanged. Electrical distribution data is available upon request.

List of Affected Standard Parts:

Part Number	Qualification Vehicle	
NCP114ASN120T1G		
NCP114ASN150T1G		
NCP114ASN180T1G		
NCP114ASN250T1G		
NCP114ASN260T1G		
NCP114ASN270T1G	NCP114xSNyyy	
NCP114ASN280T1G		
NCP114ASN290T1G		
NCP114ASN300T1G		
NCP114ASN330T1G		
NCP114BSN330T1G		